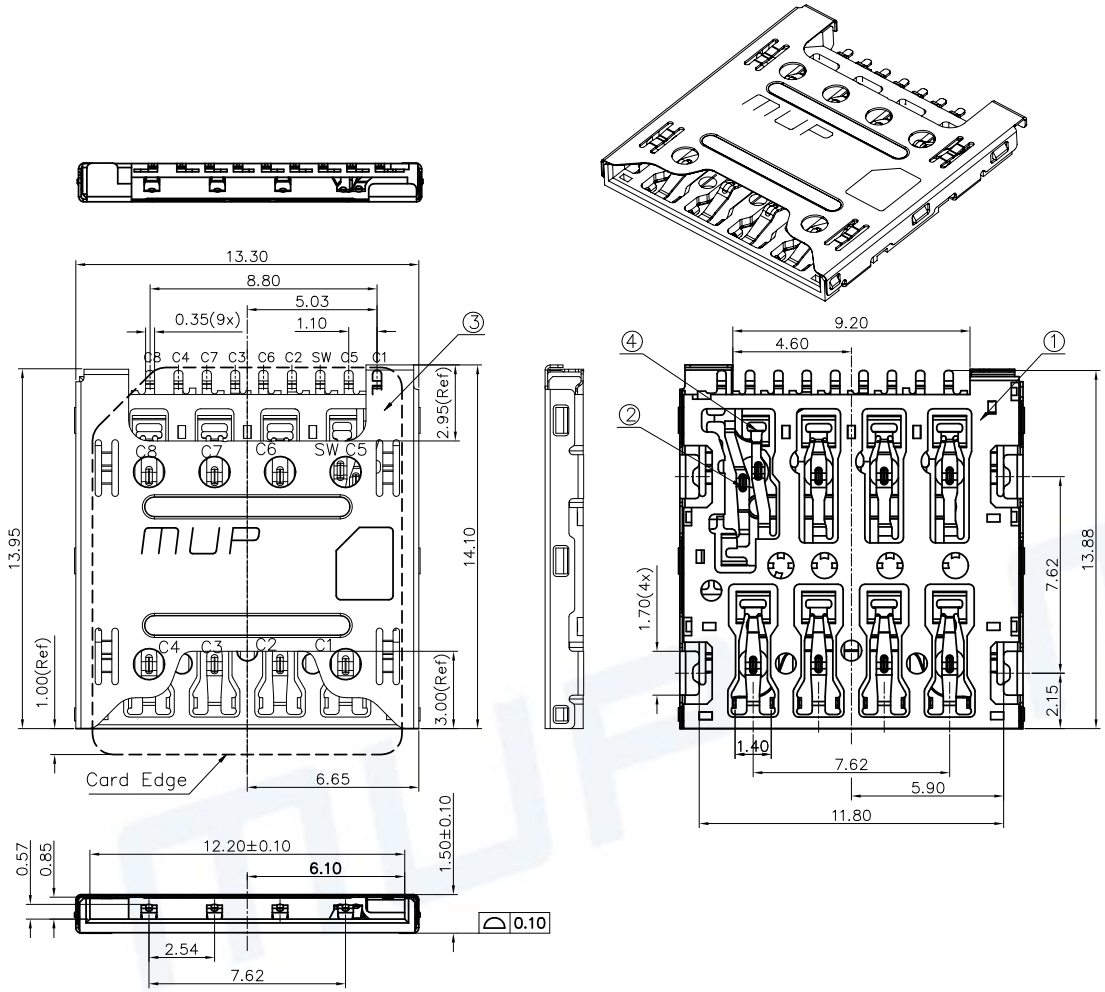
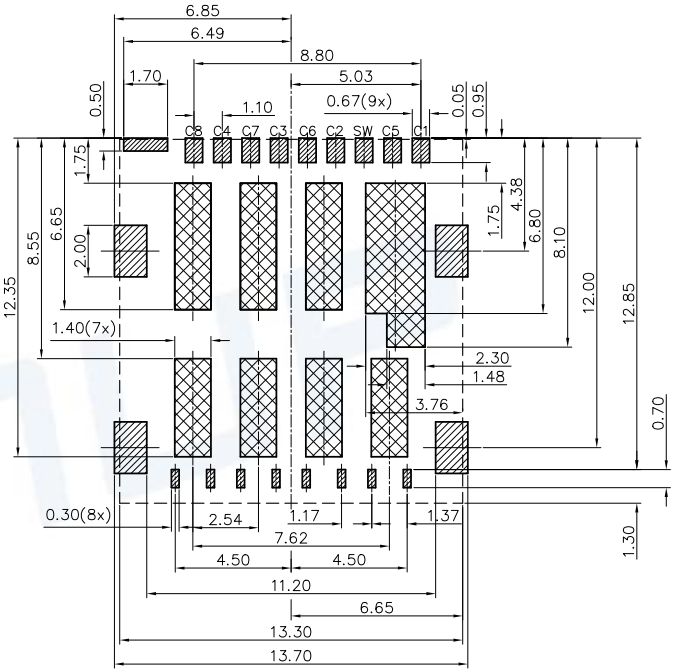
REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
1	NEW			Henry	2017/01/03
2	Original Model C793-1			Henry	2023/10/20





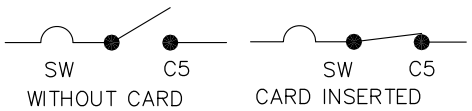
RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

PAD AREA
CONNECTOR OUTLINE
NO PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS
1.General Characteristics
Dimensions:14.10LX13.30WX1.50H mm
Weight:Approx 0.60±0.2g
Durability:2,000 cycles min.
2.Electrical Characteristics
Contact resisitance:50mΩ typical, 100mΩMax
Insulation resistance:>1000MΩ/500V DC
3.Solderability
Vaporphase:215°C, 30sec.Max
IR reflow:260°C,5sec.Max
Manual soldering:370°C.3sec.Max
4.Environmental Characteristics
Operating remperature:-40°C~+85°C
Operating humidity:10%~+95%RH

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	OPEN
CARD INSERTED	CLOSED



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SW	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

PROJ. | UNIT mm | SCALE 1:1

CUSTOMER DRAWING

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **Micro SIM Card Connector**

MODEL NO: **MUP-C7093-01**

TYPE : **H1.50mm 8PIN**

DRAWN	Henry Jan.03.2017	DWG NO.: DWG-C7093-01-01
CHECKED	Henry Jan.03.2017	SHEET 1/1 / REVISION 2
APPROVAL	Simon Jan.03.2017	

PROCESS COMPLIANT